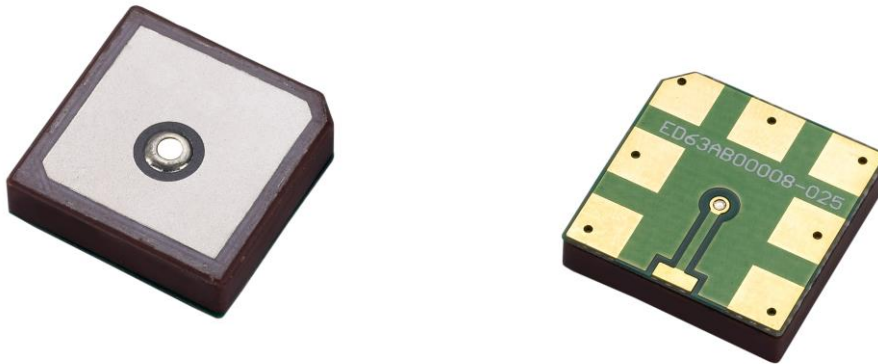


## SPECIFICATION

Part No. : **SGP.1575.18.4.C.02**

Product Name : GPS/GALILEO SMT Patch Antenna

Features : 18mm\*18mm\*4.5mm  
1575MHz Centre Frequency  
Patent Pending  
RoHS ✓



# 1. Introduction

This ceramic GPS patch antenna is based on smart **XtremeGain™** technology. It is mounted via SMT process and has been selected as optimal solution for the 45\*45mm ground plane.

# 2. Specification

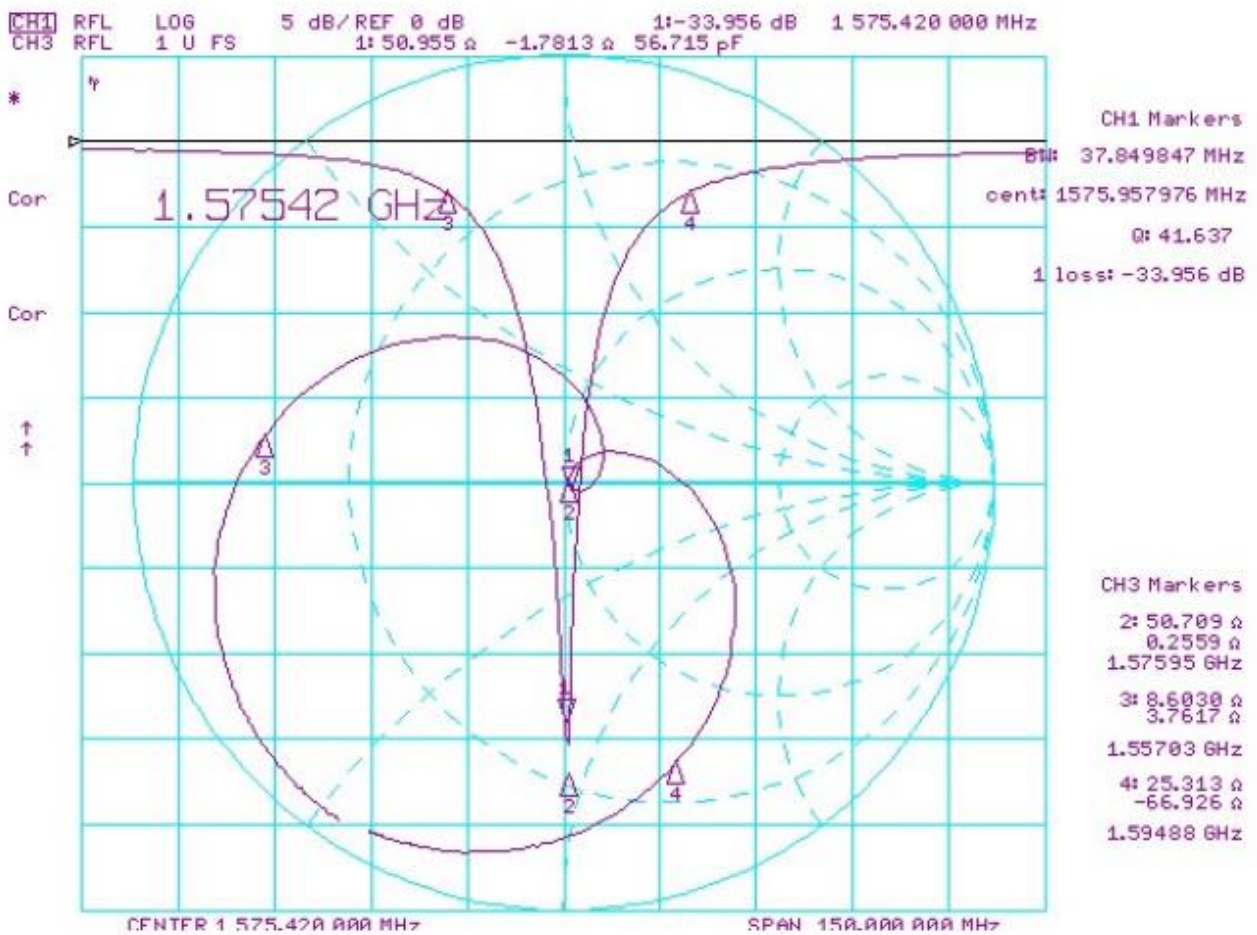
## Original Patch Specification tested on 45mm ground plane

No	Parameter	Specification	Notes
1	Range of Receiving Frequency	1575.42 MHz ± 1.023 MHz	
2	Center Frequency	1575.42 ± 3MHz	With 45*45mm ground plane
3	Bandwidth	5MHz min	Return Loss ≤ -10 dB
4	VSWR	1.5 max	
5	Gain at Zenith	+1.0 dBic typ.	
6	Gain at 10°elevation	-3.0 dBic typ.	
7	Axial Ratio	4.0 dB max	
8	Polarization	RHCP	
9	Impedance	50 Ohms	
10	Frequency Temperature Coefficient ( $\tau_f$ )	0 ± 20ppm / °C	-40°C to +85°C
11	Operating Temperature	-40°C to +85°C	

**\*\*Changes in user groundplane and environment will offset centre frequency**

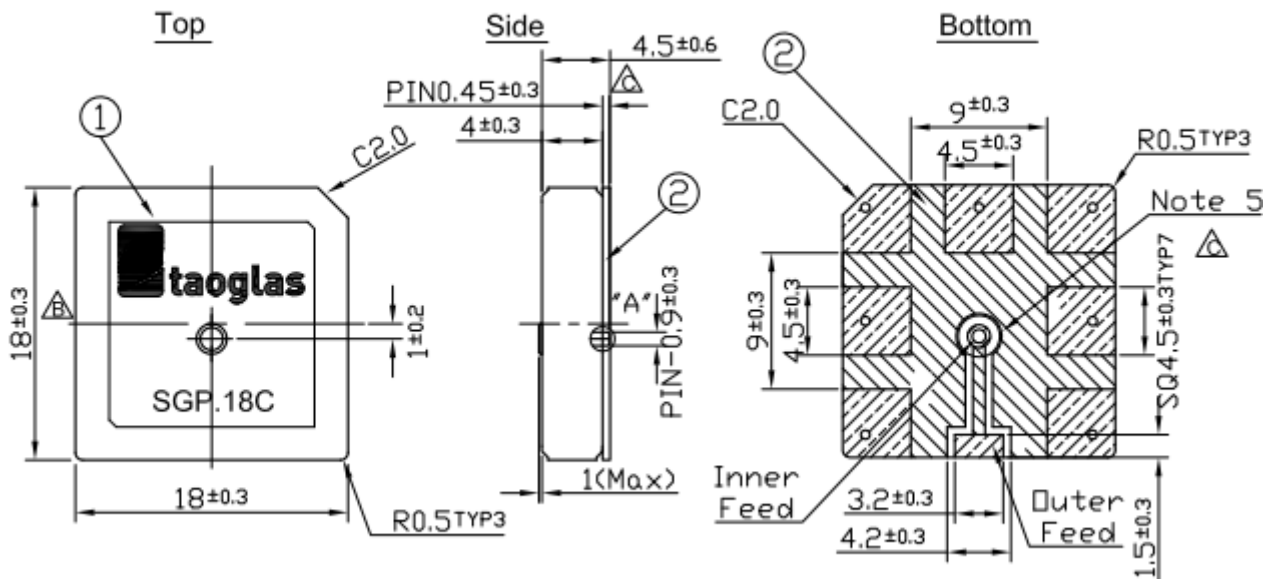
### 3. Electrical Specifications

#### 3.1 Return Loss, SWR, Impedance, measured on the test fixture





## 4. Mechanical Specifications

### 4.1 Antenna Dimensions and Drawing



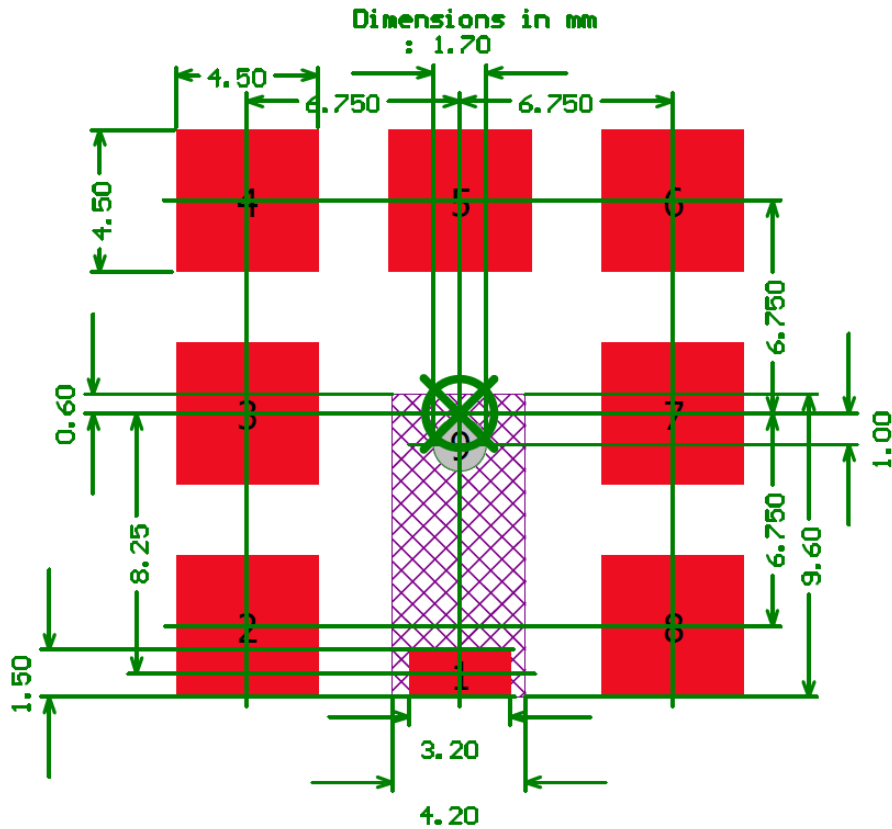
	Name	Part no.	Material	Finish	QTY
1	SGP.18 Patch 18x18x4	SGP.18C	Ceramic	Clear	1
2	SGP.18 PCB		FR 0.5t	Green	1

#### NOTE:

1. Solder mask 
2. Area to be soldered 
3. Dimension of 50 Ohm CPW dependent on individual board.
4. Matching circuit-capacitor and inductor values dependent on individual environment.
5. Must be soldered to complete antenna feed connection.

## 4.2 Antenna Footprint

### 4.2.1 Top Copper



**Copper Keepout Region**

Pads 2, 3, 4, 5, 6, 7, 8 are the same size and should be connected to GND.

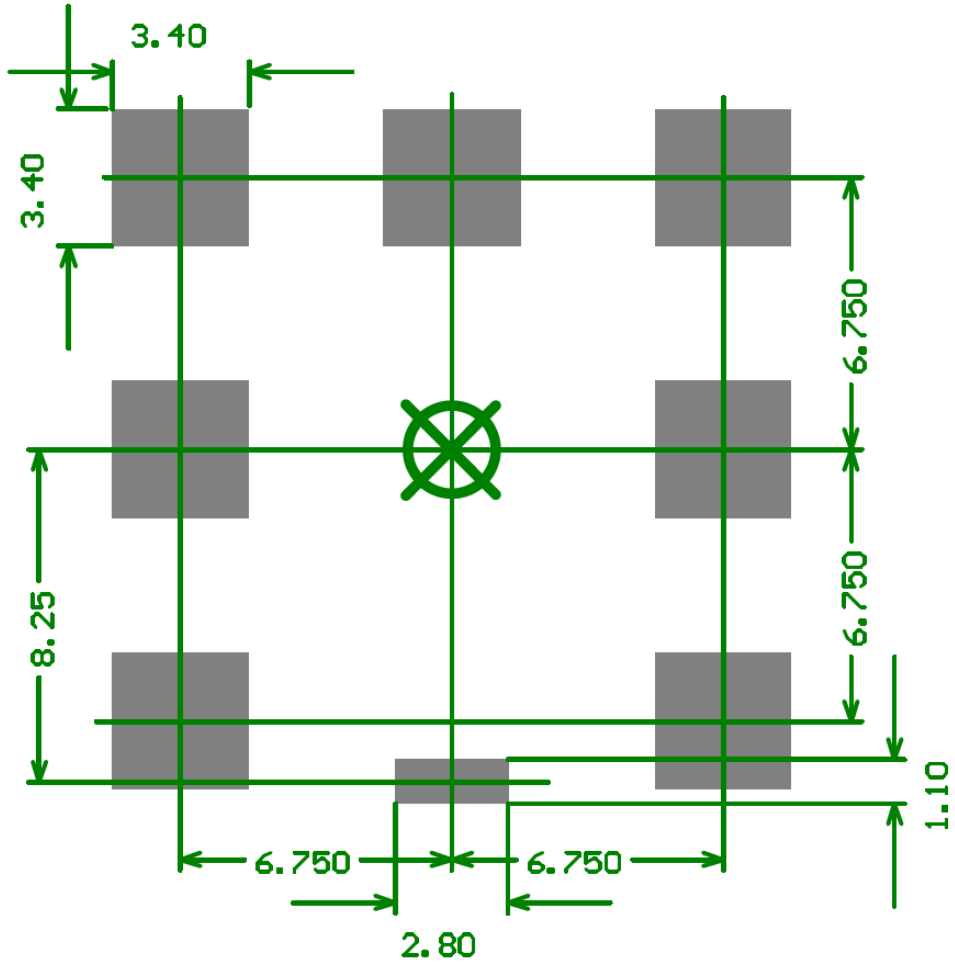
Pad 9 is a 1.70mm dia. non-plated thru-hole.

Connect 50 ohm transmission line to Pad 1.

Copper Keepout Region should extend at least 2 mm down into PCB.

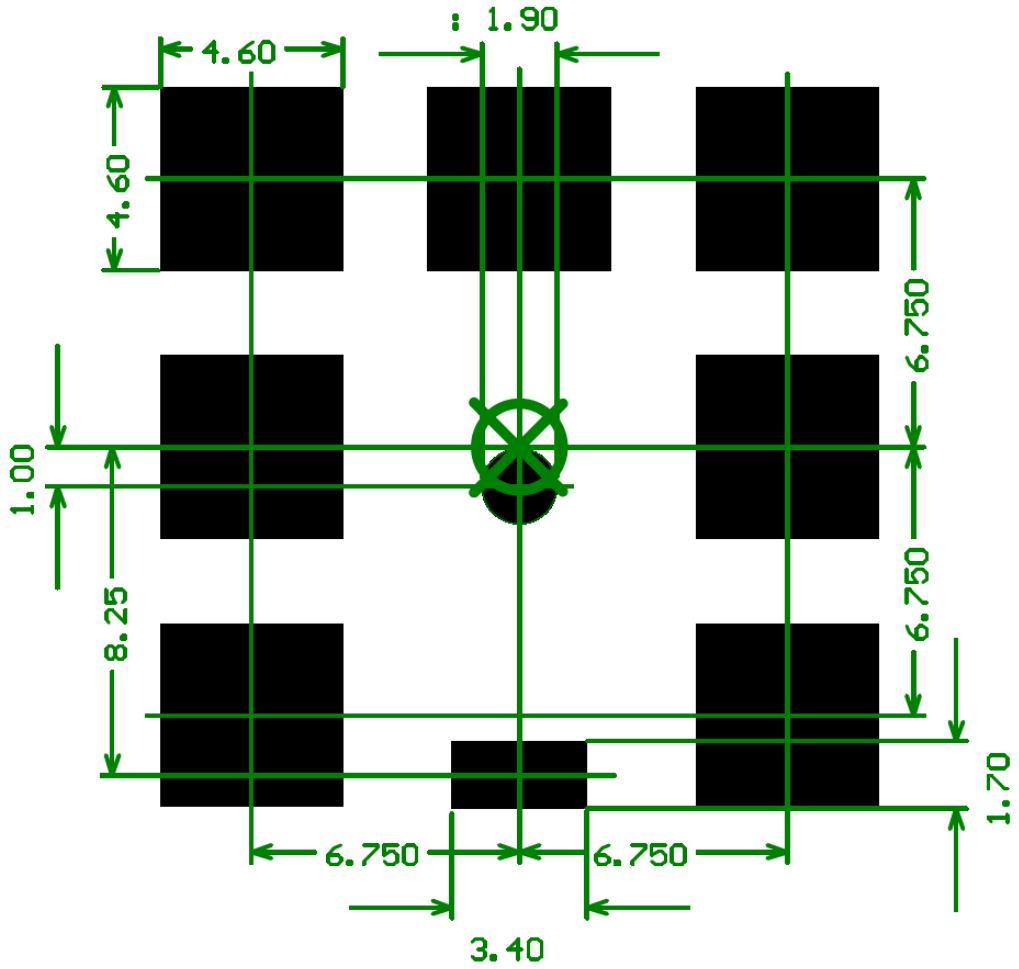
### 4.2.2 Top Paste

Dimensions in mm

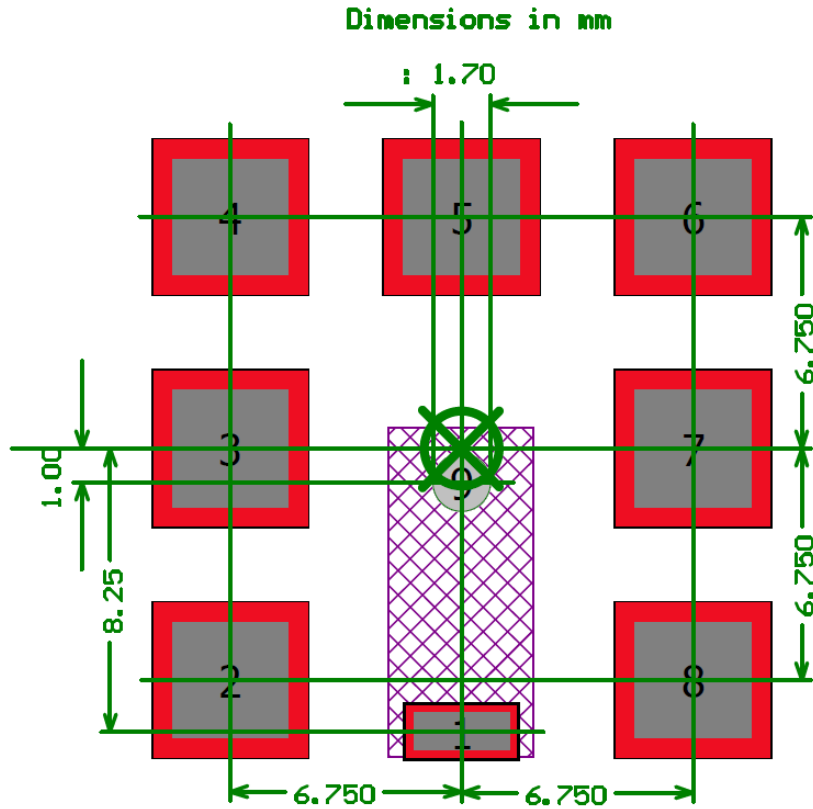


### 4.2.3 Top Mask

Dimensions in mm



### 4.2.4 Composite

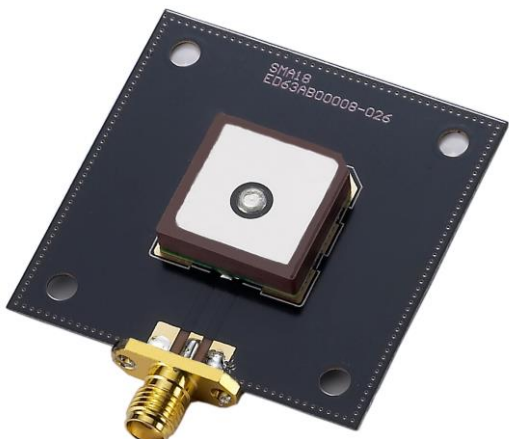
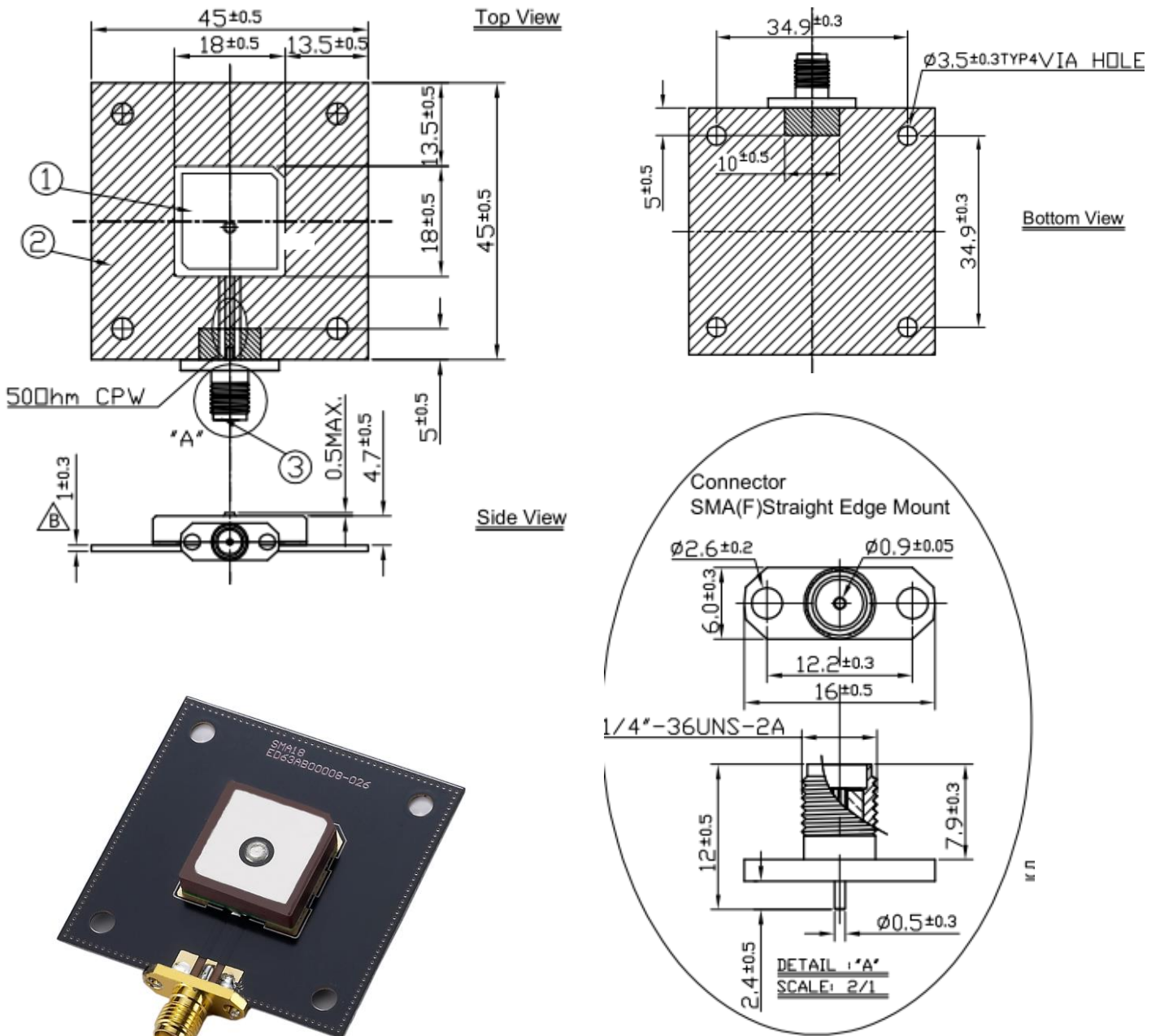


 **Copper Keepout Region**

Pads 2, 3, 4, 5, 6, 7, 8 are the same size and should be connected to GND.  
 Pad 9 is a 1.70mm dia. non-plated thru-hole.  
 Connect 50 ohm transmission line to Pad 1.  
 Copper Keepout Region should extend at least 2 mm down into PCB.



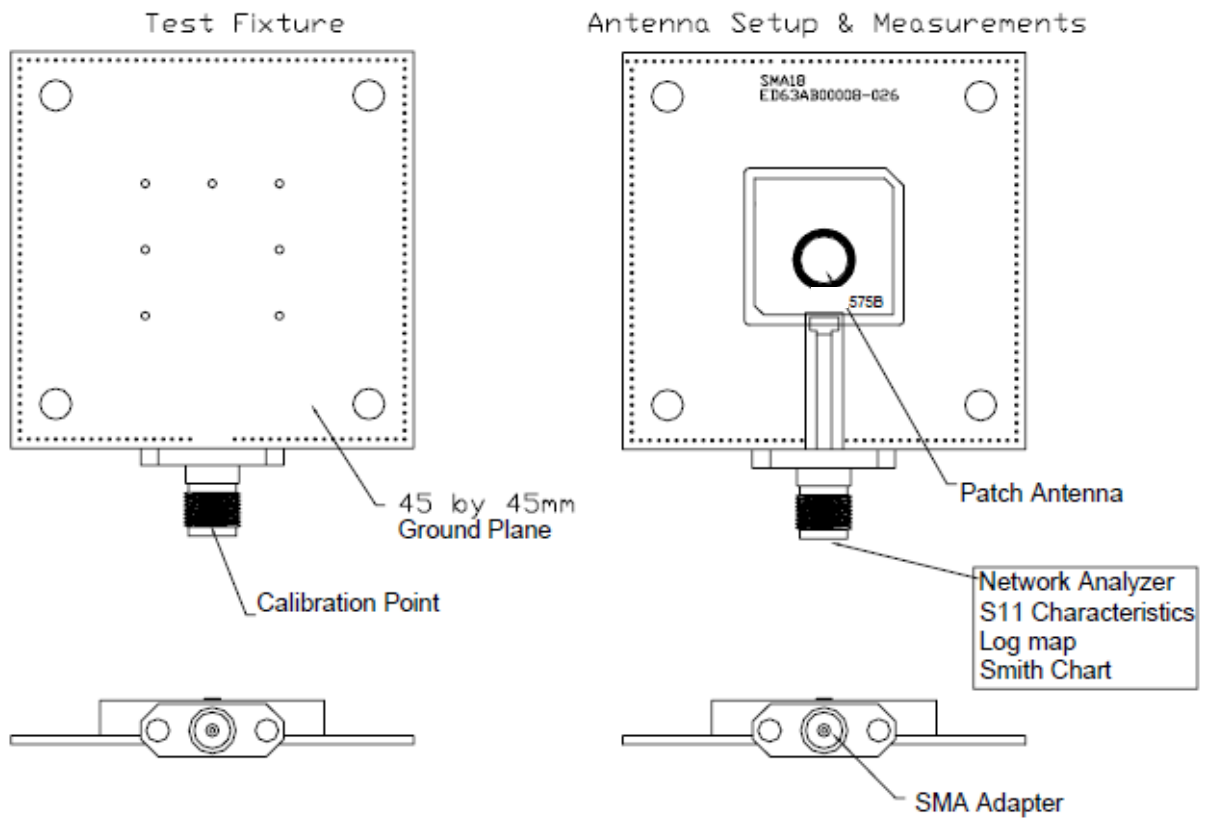
### 4.3 Test Jig and Dimension



NC  
1.5  
2.Solder Area 

		P/N	Material	Finish	QTY
1	SGP.18C	SGP.18C	Ceramic	Clear	1
2	FR4 PCB		FR4 1t	Black	1
3	SMA(F)Straight Edge Mount	SMA.F.ST.JACK.PANELM.2H.CM	Brass	Gold	1

## 4.4 Test Fixture set up and measurements

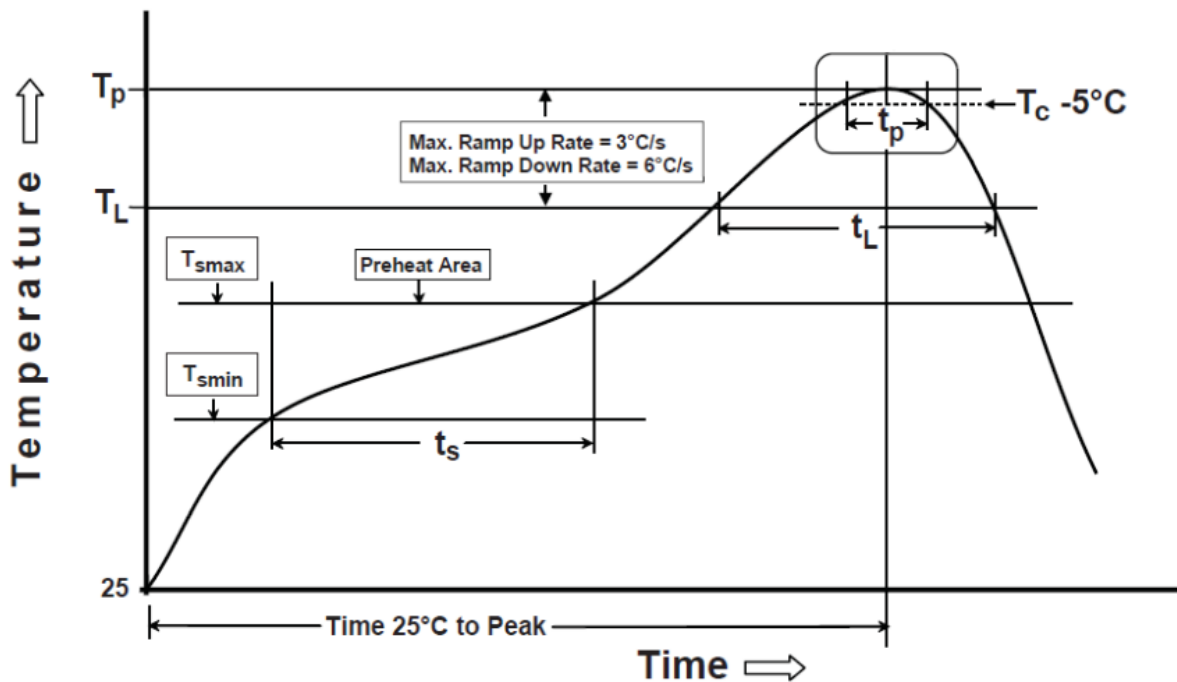


## 5. Recommended Reflow Soldering Profile

SGP.18C can be assembled following Pb-free assembly. According to the Standard IPC/JEDEC J-STD-020C, the temperature profile suggested is as follow:

Phase	Profile Features	Pb-Free Assembly (SnAgCu)
PREHEAT	Temperature Min( $T_{smin}$ )	150°C
	Temperature Max( $T_{smax}$ )	200°C
	Time( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ )	60-120 seconds
RAMP-UP	Avg. Ramp-up Rate ( $T_{smax}$ to $T_P$ )	3°C/second(max)
REFLOW	Temperature( $T_L$ )	217°C
	Total Time above $T_L$ ( $t_L$ )	30-100 seconds
PEAK	Temperature( $T_P$ )	260°C
	Time( $t_p$ )	2-5 seconds
RAMP-DOWN	Rate	3°C/second(max)
Time from 25°C to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

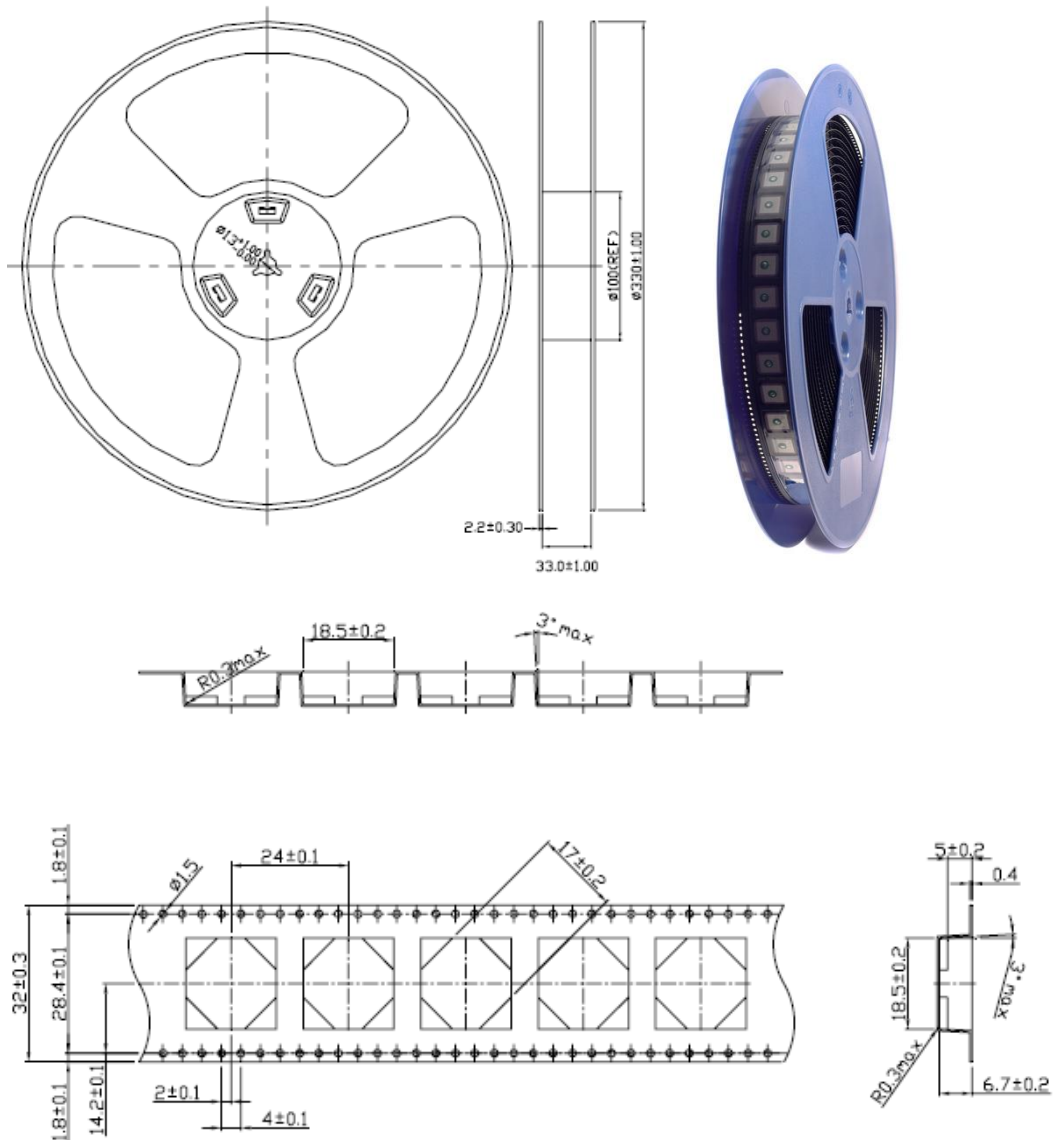
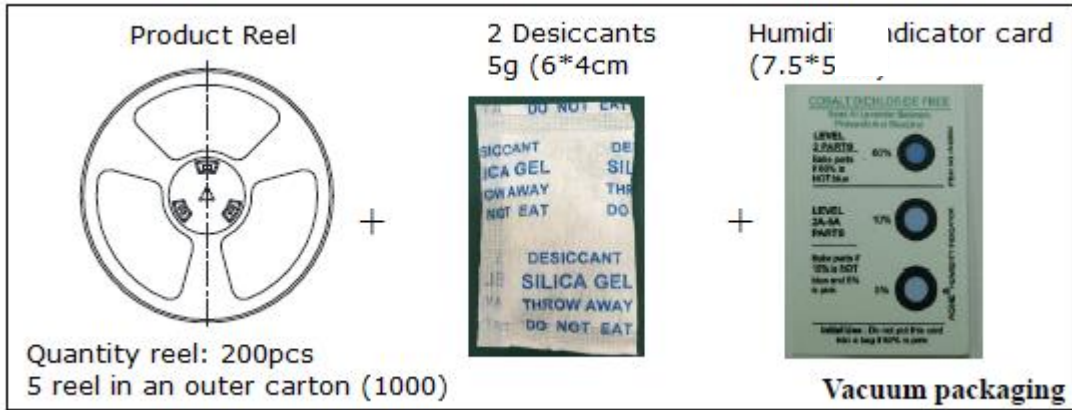
The graphic shows temperature profile for component assembly process in reflow ovens



Soldering Iron condition: Soldering iron temperature  $270^\circ\text{C} \pm 10^\circ\text{C}$ .

Apply preheating at  $120^\circ\text{C}$  for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron temperature over  $270^\circ\text{C} \pm 10^\circ\text{C}$  or 3 seconds, it will make cause component surface peeling or damage.

## 6. Packaging



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